

Title (en)

A METHOD FOR FABRICATING HIGH ASPECT RATIO ELECTRODES

Title (de)

VERFAHREN ZUR HERSTELLUNG VON ELEKTRODEN MIT GROSSEM SEITENVERHÄLTNIS

Title (fr)

PROCEDE DE FABRICATION D'ELECTRODES A GRAND ALLONGEMENT

Publication

**EP 1454358 A1 20040908 (EN)**

Application

**EP 02789028 A 20021118**

Priority

- NO 0200425 W 20021118
- NO 20016096 A 20011214

Abstract (en)

[origin: WO03052831A1] In a method for building high aspect ratio electrodes in an electrode means (E) comprising parallel electrodes (  $\epsilon_1$ ,  $\epsilon_2$ ) in a dense arrangement, the electrodes are built in a repeatedly performed sequence of successive process steps involving the use of only one and the same photomask in every patterning step, the electrodes being formed with a desired aspect ratio according to the number of times the sequence is repeated, and top surface of the electrode means planarized in a final process step.

[origin: WO03052831A1] In a method for building high aspect ratio electrodes in an electrode means ( $\epsilon_1$ ,  $\epsilon_2$ ) comprising parallel electrodes (  $\epsilon_1$ ,  $\epsilon_2$ ) in a dense arrangement, the electrodes are built in a repeatedly performed sequence of successive process steps involving the use of only one and the same photomask in every patterning step, the electrodes being formed with a desired aspect ratio according to the number of times the sequence is repeated, and top surface of the electrode means planarized in a final process step.

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**H01L 29/41**; **H01L 21/28**

IPC 8 full level

**H01L 29/41** (2006.01); **H10B 20/00** (2023.01); **H10B 99/00** (2023.01)

CPC (source: EP KR US)

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